



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Parameter	Rating	Units
Blocking Voltage	800	V_P
Load Current		
AC/DC Configuration	100	mA_{rms} / mA_{DC}
DC Configuration	180	mA_{DC}
On-Resistance (max)		
AC/DC Configuration	50	Ω
DC Configuration	14	

Features

- 800V_P Blocking Voltage
- 3750V_{rms} Input/Output Isolation
- 100% Solid State
- Low Drive Power Requirements (TTL/CMOS Compatible)
- Arc-Free With No Snubbing Circuits
- No EMI/RFI Generation
- Small 6-Pin Package
- Machine Insertable, Wave Solderable

Applications

- Instrumentation
 - Multiplexers
 - Data Acquisition
 - Electronic Switching
 - I/O Subsystems
- Meters (Watt-Hour, Water, Gas)
- Medical Equipment—Patient/Equipment Isolation
- Security
- Aerospace
- Industrial Controls

Description

PLA170 is a single-pole, normally open (1-Form-A) Solid State Relay that uses optically coupled MOSFET technology to provide an enhanced input-to-output isolation of 3750V_{rms}.

Its optically coupled outputs, which use the patented OptoMOS architecture, are controlled by a highly efficient GaAlAs infrared LED.

Designed to replace electromechanical relays, the PLA170 offers the superior reliability associated with solid state devices, and provides bounce-free switching in a more compact surface mount or thru-hole package.

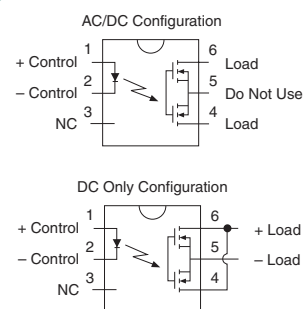
Approvals

- UL Recognized Component: File E76270
- CSA Certified Component: Certificate 1175739
- EN/IEC 60950-1 Certified Component:
TUV Certificate B 09 07 49410 004

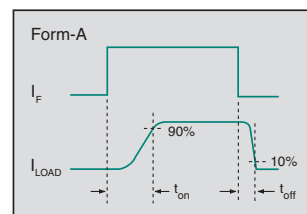
Ordering Information

Part #	Description
PLA170	6-Pin DIP (50/tube)
PLA170S	6-Pin Surface Mount (50/tube)
PLA170STR	6-Pin Surface Mount (1000/Reel)

Pin Configuration



Switching Characteristics of Normally Open Devices



Absolute Maximum Ratings @ 25°C

Parameter	Ratings	Units
Blocking Voltage	800	V _P
Reverse Input Voltage	5	V
Input Control Current	50	mA
Peak (10ms)	1	A
Input Power Dissipation ¹	150	mW
Total Power Dissipation ²	800	mW
Isolation Voltage, Input to Output	3750	V _{rms}
Operational Temperature	-40 to +85	°C
Storage Temperature	-40 to +125	°C

¹ Derate linearly 1.33 mW / °C

² Derate linearly 6.67 mW / °C

Absolute Maximum Ratings are stress ratings. Stresses in excess of these ratings can cause permanent damage to the device. Functional operation of the device at conditions beyond those indicated in the operational sections of this data sheet is not implied.

Electrical Characteristics @ 25°C

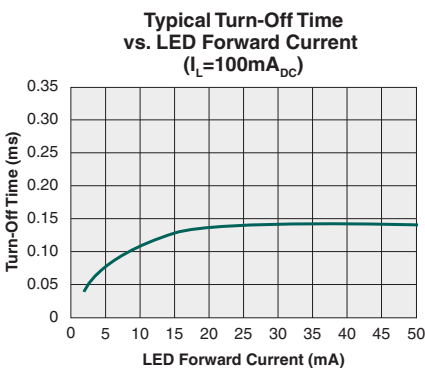
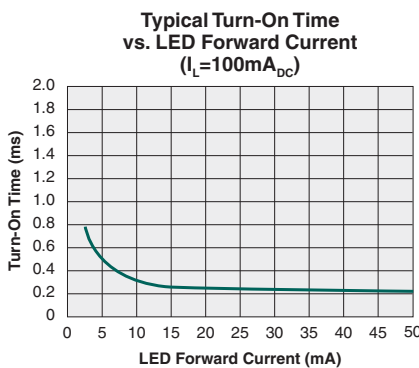
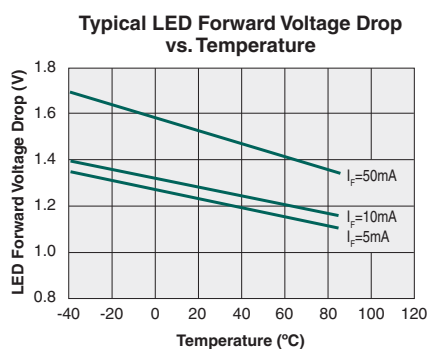
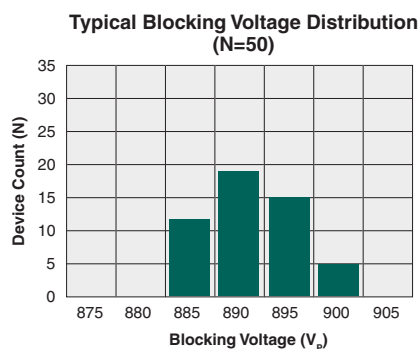
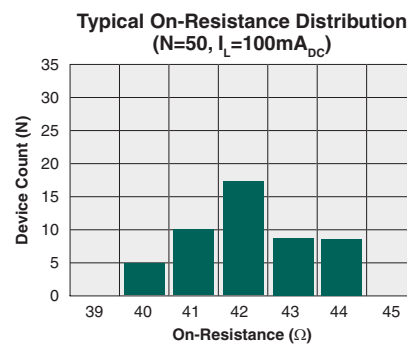
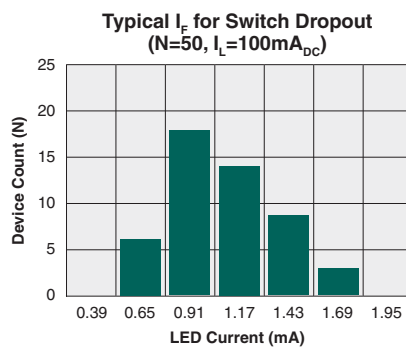
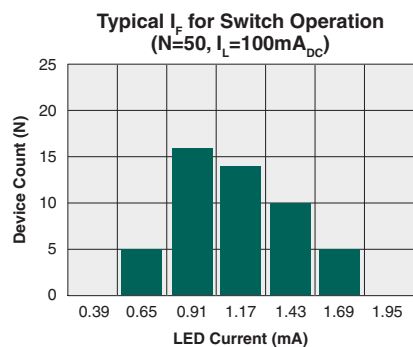
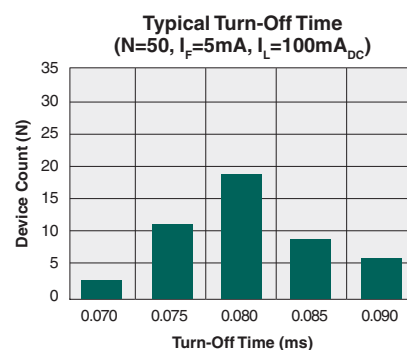
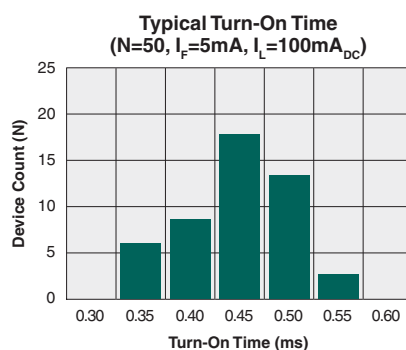
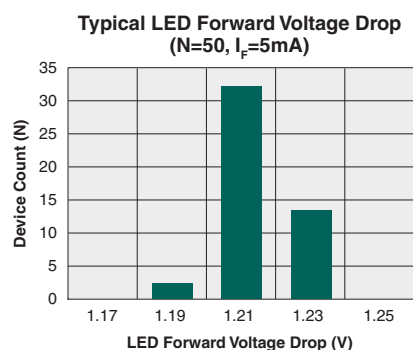
Parameter	Conditions	Symbol	Min	Typ	Max	Units
Output Characteristics						
Load Current, Continuous						
AC/DC Configuration ¹	-	I _L	-	-	100	mA _{rms} / mA _{DC}
DC Configuration					180	mA _{DC}
Peak Load Current	t=10ms	I _{LPK}	-	-	±350	mA _P
On-Resistance ²						
AC/DC Configuration	I _L =Load Current	R _{ON}	-	-	50	Ω
DC Configuration			-	-	14	
Off-State Leakage Current	V _L =800V _P	I _{LEAK}	-	-	1	μA
Switching Speeds						
Turn-On	I _F =5mA, V _L =10V	t _{on}	-	-	5	ms
Turn-Off		t _{off}	-	-	5	
Output Capacitance	V _L =50V, f=1MHz	C _{OUT}	-	50	-	pF
Input Characteristics						
Input Control Current to Activate ³	I _L =Load Current	I _F	-	-	5	mA
Input Control Current to Deactivate	-	I _F	0.3	0.7	-	mA
Input Voltage Drop	I _F =5mA	V _F	0.9	1.2	1.4	V
Reverse Input Current	V _R =5V	I _R	-	-	10	μA
Common Characteristics						
Input to Output Capacitance	-	C _{I/O}	-	3	-	pF

¹ Load derates linearly from 100mA @ 25°C to 90mA @ 80°C.

² Measurement taken within 1 second of on-time.

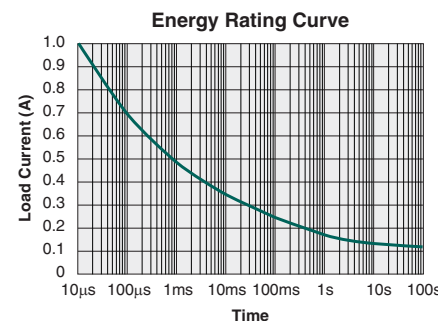
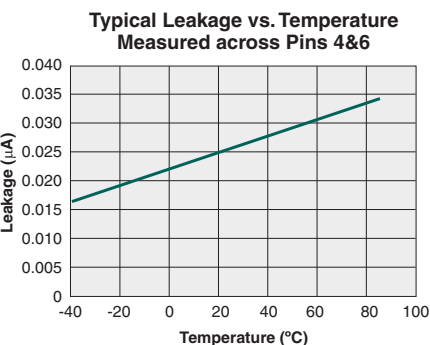
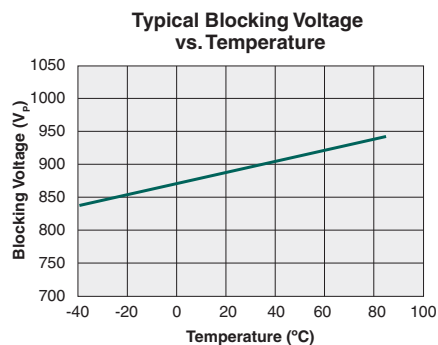
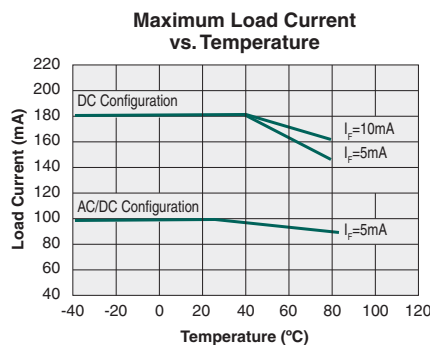
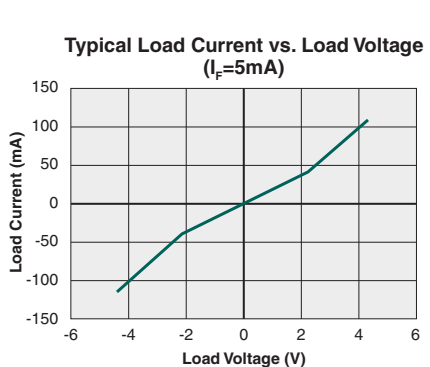
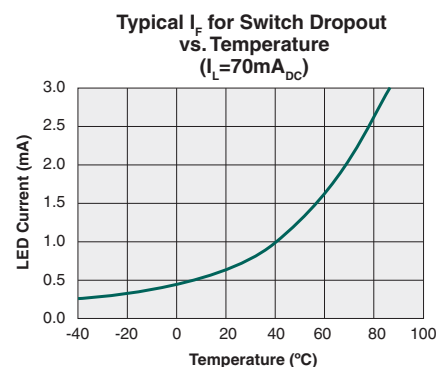
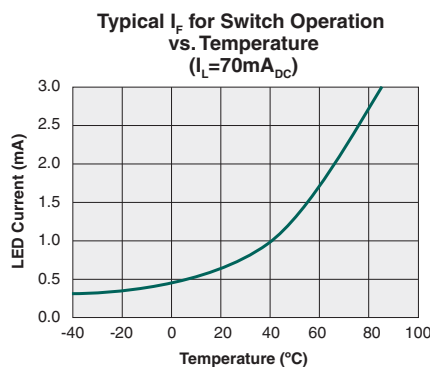
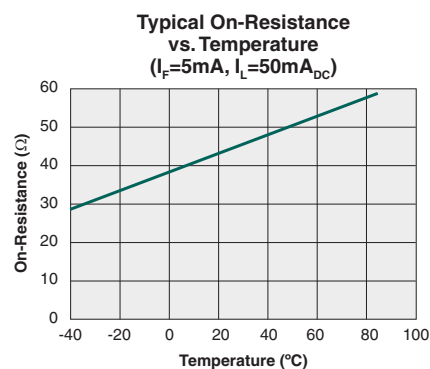
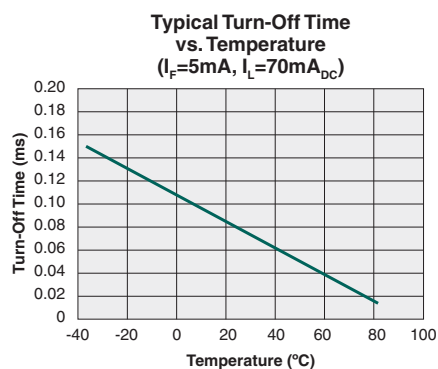
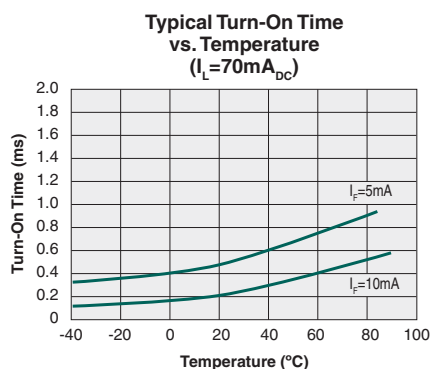
³ For applications requiring high temperature operation (greater than 60°C) a LED drive current of 10mA is recommended.

PERFORMANCE DATA @ 25°C (Unless Otherwise Noted) *



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

PERFORMANCE DATA @ 25°C (Unless Otherwise Noted) *



*The Performance data shown in the graphs above is typical of device performance. For guaranteed parameters not indicated in the written specifications, please contact our application department.

Manufacturing Information

Moisture Sensitivity



All plastic encapsulated semiconductor packages are susceptible to moisture ingress. IXYS Integrated Circuits Division classified all of its plastic encapsulated devices for moisture sensitivity according to the latest version of the joint industry standard, **IPC/JEDEC J-STD-020**, in force at the time of product evaluation. We test all of our products to the maximum conditions set forth in the standard, and guarantee proper operation of our devices when handled according to the limitations and information in that standard as well as to any limitations set forth in the information or standards referenced below.

Failure to adhere to the warnings or limitations as established by the listed specifications could result in reduced product performance, reduction of operable life, and/or reduction of overall reliability.

This product carries a **Moisture Sensitivity Level (MSL) rating** as shown below, and should be handled according to the requirements of the latest version of the joint industry standard **IPC/JEDEC J-STD-033**.

Device	Moisture Sensitivity Level (MSL) Rating
PLA170 / PLA170S	MSL 1

ESD Sensitivity



This product is **ESD Sensitive**, and should be handled according to the industry standard **JESD-625**.

Reflow Profile

This product has a maximum body temperature and time rating as shown below. All other guidelines of **J-STD-020** must be observed.

Device	Maximum Temperature x Time
PLA170 / PLA170S	250°C for 30 seconds

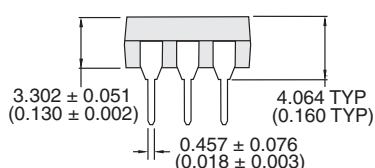
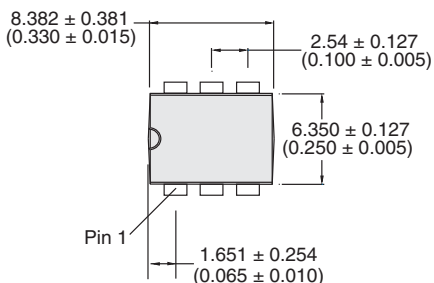
Board Wash

IXYS Integrated Circuits Division recommends the use of no-clean flux formulations. However, board washing to remove flux residue is acceptable. Since IXYS Integrated Circuits Division employs the use of silicone coating as an optical waveguide in many of its optically isolated products, the use of a short drying bake could be necessary if a wash is used after solder reflow processes. Chlorine- or Fluorine-based solvents or fluxes should not be used. Cleaning methods that employ ultrasonic energy should not be used.

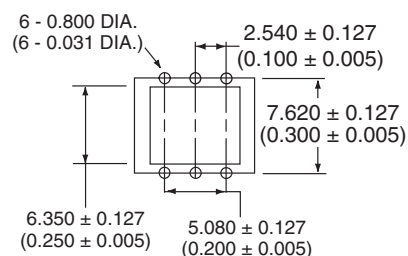


Mechanical Dimensions

PLA170

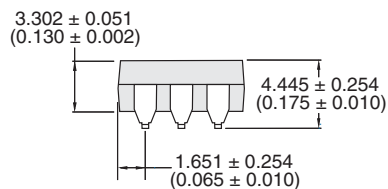
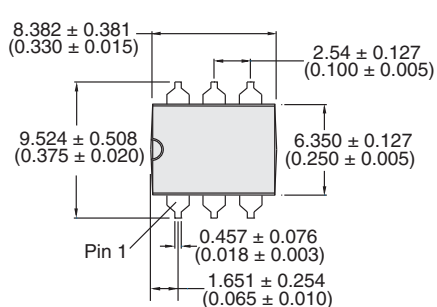


PCB Hole Pattern

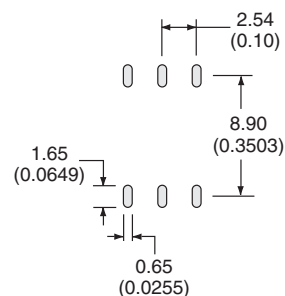


Dimensions
mm
(inches)

PLA170S

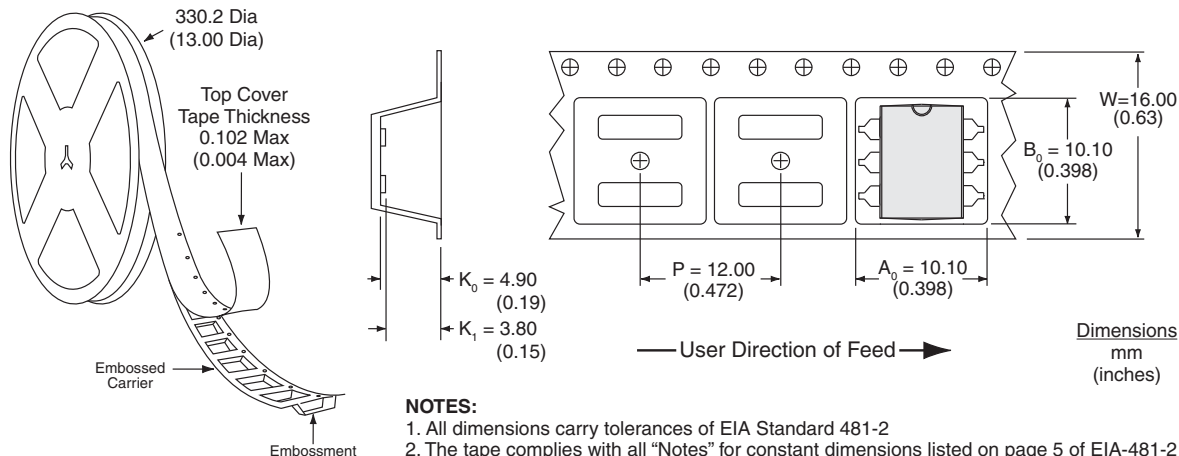


PCB Land Pattern



Dimensions
mm
(inches)

PLA170STR Tape & Reel



For additional information please visit our website at: www.ixysic.com

IXYS Integrated Circuits Division makes no representations or warranties with respect to the accuracy or completeness of the contents of this publication and reserves the right to make changes to specifications and product descriptions at any time without notice. Neither circuit patent licenses nor indemnity are expressed or implied. Except as set forth in IXYS Integrated Circuits Division's Standard Terms and Conditions of Sale, IXYS Integrated Circuits Division assumes no liability whatsoever, and disclaims any express or implied warranty, relating to its products including, but not limited to, the implied warranty of merchantability, fitness for a particular purpose, or infringement of any intellectual property right.

The products described in this document are not designed, intended, authorized or warranted for use as components in systems intended for surgical implant into the body, or in other applications intended to support or sustain life, or where malfunction of IXYS Integrated Circuits Division's product may result in direct physical harm, injury, or death to a person or severe property or environmental damage. IXYS Integrated Circuits Division reserves the right to discontinue or make changes to its products at any time without notice.